ALL ARTWORK VIEWED FROM TOP SIDE  BOARD #: TIDM-01527  REV: E2  SUN REV: Not In VersionControl

LAYER NAME =  TID #: TIDM-01527

PLOT NAME = Bottom Solder Mask  GENERATED: 09-Dec-17  2:28:28 PM  TEXAS INSTRUMENTS
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<th>BOARD #: TIDA-01527</th>
<th>REV #: 2</th>
<th>SVN REV #: Not In Version Control</th>
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<td>LAYER NAME = Bottom Overlay</td>
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<td>2:28:29 PM</td>
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